

Min reflow profile requirements for solderability testing		
Parameter	Reference	Specification
Average temperature gradient in preheating		2.5 °C/S
Soak time	$t_{soak}$	2-3 minutes
Time above 217 °C	$t_1$	Max 30 sec
Peak temperature in reflow	$T_2$	230 °C(-0/+5 °C)
Time at peak temperature	$t_2$	10s
Temperature gradient in cooling		Max -6 °C/s

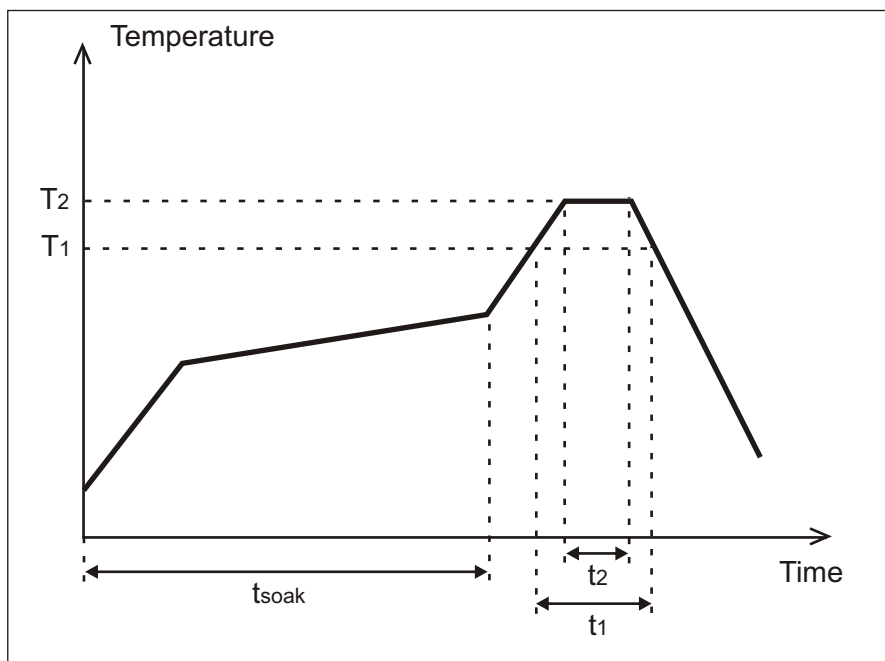


Figure 1. Reflow profile for solderability testing.

Max reflow profile requirements for solderability testing		
Parameter	Reference	Specification
Average temperature gradient in preheating		2.5 °C/s
Soak time	$t_{soak}$	2-3 minutes
Time above 217 °C	$t_1$	Max 60 sec
Time above 230 °C	$t_2$	Max 50 sec
Time above 250 °C	$t_3$	Max 10 sec
Peak temperature in reflow	$T_{peak}$	260 °C(-5/+0 °C)
Temperature gradient in cooling		Max -6 °C/s

Note: 1. Can withstand maximum of 3 cycles of profile above.

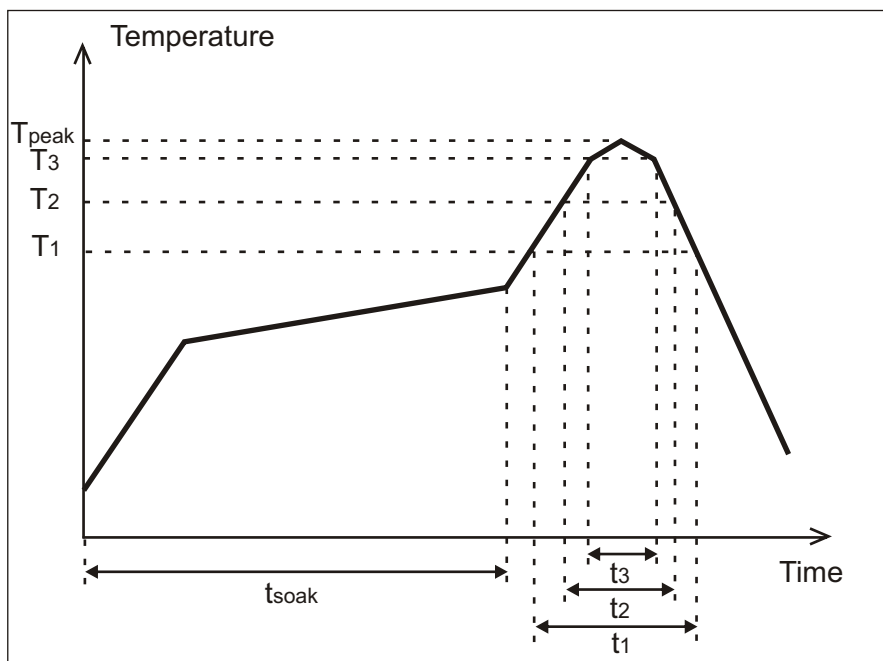


Figure 2. Reflow profile for soldering heat resistance testing.